

**Description:**

A low noise, high PSRR and ultra low dropout linear regulator SULR1190 is optimized for low ESR ceramic capacitors operation with 1A continuous current.

The SULR1190 offers high precision output voltage of  $\pm 2\%$  tolerance. Output voltage can also be adjusted for those other than the preset values.

A noise bypass pin is available for further reduction of output noise. The bypass pin could be floating if it's unnecessary. At 1A load current and 2.8V output voltage, a 440mV dropout is performed. The quality of low quiescent current and low dropout voltage makes this device ideal for battery power applications. The high ripple rejection and low noise of the SULR1190 provide enhanced performances for critical applications such as cellular phones, and PDAs.

In addition, a logic-level shutdown input is included, which reduce supply current to less than 0.1 $\mu$ A (typ.) in shutdown mode with fast turn-on time less than 100 $\mu$ s. The SULR1190's current limit and thermal protection provide protection against any overload condition that would create excessive junction temperatures.

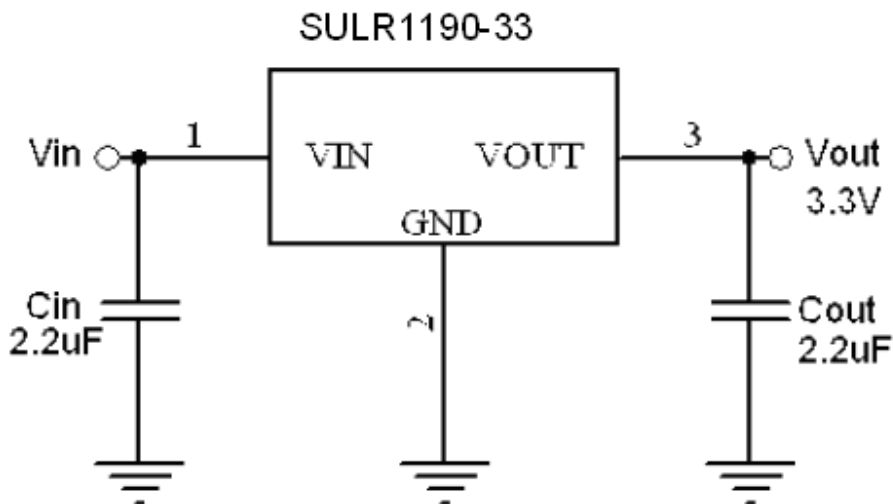
**Features:**

- Guaranteed 1A Output Current.
- Fast Response in Line/Load Transient
- Wide Operating Voltage Ranges: 2.3V to 6.0V.
- 0.1 $\mu$ A Shutdown Standby Current
- Low Quiescent Current: < 60 $\mu$ A.
- Fixed: 1.2V, 1.5V, 1.8V, 2.0V, 2.5V, 2.7V, 3.0V, 3.3V, 3.5V, 3.7V, 3.8V Output Voltage.
- Output Voltage are available from 0.8~5.0V in Adjustable Version.
- Low Dropout: 440mV at 1A and 2.8V output voltage.
- High PSRR: 70dB at 1KHz.
- Active Low or High Shutdown Control. Current Limit and Thermal Protection.
- Available in  $\pm 2\%$  Output Tolerance.
- Available in SOT-223 & TO-220 (3 pin) & SOP- 8 Exposed Pad (Heat Sink) and TO-252 & TO-263 (3 pin) Package.

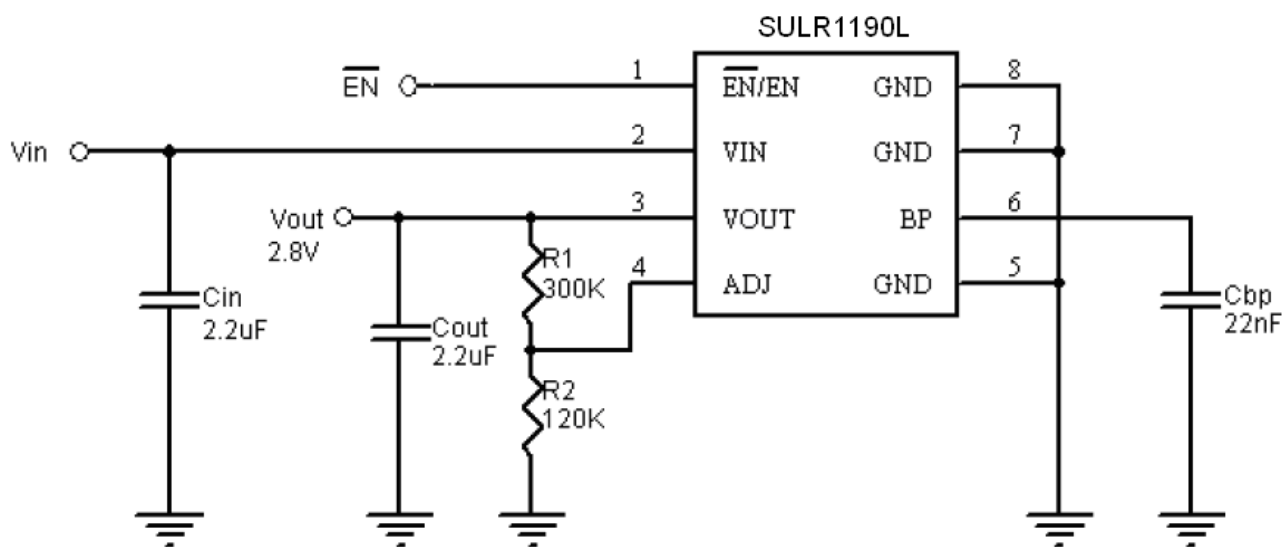
**Applications:**

- LCD TV, LCD Monitor, DPF
- Networking
- STB
- DVD, HDD Driver
- Portable AV Equipment
- PC Peripherals

Typical application circuit:



Fixed Linear Regulator



Adjustable Linear Regulator in SOP-8 Exposed Pad Package



Ordering Information:

SULR1190-XXXXX

PACKING TYPE  
TB: TUBE  
TR: TAPING & REEL

PACKAGING TYPE  
T: TO-252  
R: TO-263  
V: TO-220  
G: SOT-223  
M: SOP-8

OUTPUT VOLTAGE  
08: 0.8V  
10: 1.0V  
12: 1.2V  
15: 1.5V  
18: 1.8V  
20: 2.0V  
25: 2.5V  
27: 2.7V  
30: 3.0V  
33: 3.3V  
35: 3.5V  
37: 3.7V  
38: 3.8V  
(Of a unit of 0.1V within  
0.8~4.5V, additional voltage  
versions are available on  
demand)

Example: SULR1190-18TTR  
→ 1.8V version in TO-252 Lead Free  
Package & Taping & Reel Packing Type

PIN CONFIGURATION	
TO-252 TOP VIEW  1: ADJ (GND) 2: VOUT (TAB) 3: VIN	
TO-263 TOP VIEW  1: ADJ (GND) 2: VOUT (TAB) 3: VIN	
TO-220 FRONT VIEW  1: ADJ (GND) 2: VOUT (TAB) 3: VIN	
SOT-223 FRONT VIEW  1: ADJ (GND) 2: VOUT (TAB) 3: VIN	
SOP-8 Exposed Pad (Heat Sink) TOP VIEW  1: EN / EN 2: VIN 3: VOUT 4: ADJ 5: GND (TAB) 6: BP 7: GND (TAB) 8: GND (TAB)	



**Technical Data**  
**Data Sheet N1577, Rev. -**  
**Ordering Information (Continued)**

**Ultra LDO 1A Linear Regulator With**

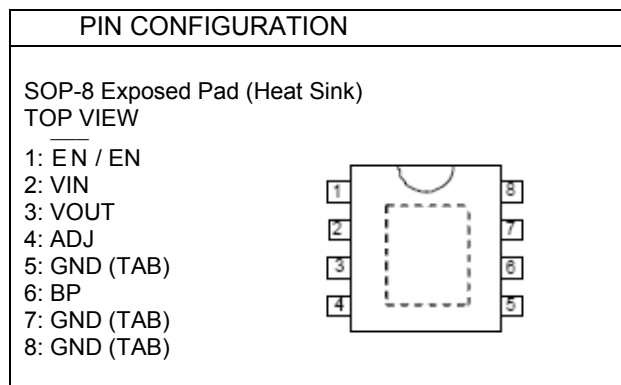
SULR1190H-XXXXX

PACKING TYPE  
 TB: TUBE  
 TR: TAPING & REEL

PACKAGING TYPE  
 T: TO-252  
 R: TO-263  
 V: TO-220  
 G: SOT-223  
 M: SOP-8

OUTPUT VOLTAGE  
 08: 0.8V  
 10: 1.0V  
 12: 1.2V  
 15: 1.5V  
 18: 1.8V  
 20: 2.0V  
 25: 2.5V  
 27: 2.7V  
 30: 3.0V  
 33: 3.3V  
 35: 3.5V  
 37: 3.7V  
 38: 3.8V  
 (Of a unit of 0.1V within  
 0.8~4.5V, additional voltage  
 versions are available on  
 demand)

ENABLE TYPE  
 L: Chip Enable Low  
 H: Chip Enable High



Example: SULR1190H-18MTR

→ Chip Enable High, 1.8V Version, in SOP-8 Green Package & Tape & Reel Packing Type

Output Voltage Could Be Adjusted from 0.8V to 5.0V by External Resistors.

**Marking Diagram:**

Part No.	Marking
SULR1190-xxGTR	HBxxG

xx represents output voltage. (08=0.8V, 09=0.9V, ....., 44=4.4V, 45=4.5V)

- China - Germany - Korea - Singapore - United States •
- <http://www.smc-diodes.com> - [sales@smc-diodes.com](mailto:sales@smc-diodes.com) •



**Absolute Maximum Ratings:**

Input Voltage .....	7V
EN Pin Voltage .....	7V
Noise Bypass Terminal Voltage .....	7V
Operating Temperature Range .....	-40°C to 85°C
Maximum Junction Temperature .....	150°C
Storage Temperature Range .....	-65°C ~ 150°C
Lead Temperature (Soldering) 10 sec. ....	260°C
Thermal Resistance Junction to Case TO-252 .....	8°C/W
TO-263, TO-220.....	3°C/W
SOT-223.....	15°C/W
SOP-8 (Exposed Pad*).....	15°C /W
Thermal Resistance Junction to Ambient SOT-223 .....	130°C/W
(Assume no ambient airflow, no heatsink) TO-263 .....	60°C/W
TO-252 .....	100°C/W
TO-220.....	50°C/W
(Assume no ambient airflow) SOP-8 (Exposed Pad*).....	60°C /W

**Absolute Maximum Ratings are those values beyond which the life of a device may be impaired.**

\* The package is placed on a two layers PCB with 2 ounces copper and 2 square inch, connected by 8 vias

**Electrical Characteristics**
**( $C_{IN} = C_{OUT} = 2.2\mu F$ ,  $C_{BP} = 22nF$ ,  $V_{IN} = V_{OUT} + 1V$ ,  $T_J = 25^\circ C$ , unless otherwise specified) (Note 1)**

PARAMETER	TEST CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Input Voltage		$V_{IN}$	2.3		6.0	V
Output Voltage Tolerance	$I_{OUT} = 1\text{ mA}$	$V_{OUT}$	-2		2	%
Continuous Output Current		$I_{OUT}$	1.0			A
Quiescent Current	Chip Enable Low, $V_{EN} \leq 0.4V$ , $I_{OUT} = 0\text{ mA}$ Chip Enable High, $V_{EN} \geq 1.6V$ , $I_{OUT} = 0\text{ mA}$	$I_Q$		60	110	$\mu A$
GND Pin Current	Chip Enable Low, $V_{EN} \leq 0.4V$ , $I_{OUT} = 1A$ Chip Enable High, $V_{EN} \geq 1.6V$ , $I_{OUT} = 1A$	$I_{GND}$		60	110	$\mu A$
Standby Current	Chip Enable Low, $V_{EN} = V_{IN}$ Chip Enable High, $V_{EN} = 0$	$I_{STBY}$		0.1	0.5	$\mu A$
Output Current Limit	$R_{LOAD} = 0.1\Omega$	$I_{IL}$	1.1	1.6	2.2	A
Dropout Voltage	$I_{OUT} = 1A$ , $0.8V < V_{OUT} < 2V$	$V_{DROP}$			1500	mV
	$I_{OUT} = 1A$ , $2V < V_{OUT} < 2.8V$				500 900	
	$I_{OUT} = 1A$ , $V_{OUT} > 2.8V$				440 700	
Line Regulation	$V_{IN} = V_{OUT} + 1V$ to 6.0V	$\Delta V_{LIR}$			10	mV
Load Regulation	$I_{OUT} = 1mA$ to 1A	$\Delta V_{LOR}$			1 20	mV
Ripple Rejection (Note 2)	$f = 1KHz$ , Ripple = 0.5Vp-p,	PSRR			70	dB
Output Noise Voltage	$C_{BP} = 22nF$ , $f = 10 \sim 100KHz$				24	$\mu V_{rms}$
Temperature Coefficient		TC			50	ppm/ $^\circ C$
Thermal Shutdown Temperature	$V_{IN} = V_{OUT} + 1V$	$T_{SD}$			150	$^\circ C$
Thermal Shutdown Hysteresis		$\Delta T_{SD}$			20	$^\circ C$
<b>ADJ Pin Specifications</b>						
ADJ Pin Current	$V_{ADJ} = V_{REF}$	$I_{ADJ}$			10 100	nA
ADJ Pin Threshold		$V_{TH(ADJ)}$	0.05	0.1	0.2	V
Reference Voltage Tolerance		$V_{REF}$	0.784	0.8	0.816	V



Electrical Characteristics (Continued)

PARAMETER	TEST CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
<b>Shutdown Pin Specifications</b>						
Shutdown Pin Current	$V_{EN} = V_{IN}$ or GND	$I_{EN}$		0	100	nA
Shutdown Exit Delay Time	$I_{OUT} = 30mA$	$\Delta t$		100		$\mu S$
Max Output Discharge Resistance to GND during Shutdown		$RD_{SON\_CLMP}$		20	100	$\Omega$
Shutdown Input Threshold	Chip Enable Low, Output OFF, $V_{IN} = 2.3V$ to $6.0V$ Chip Enable High, Output ON, $V_{IN} = 2.3V$ to $6.0V$	$V_{ENH}$	1.6			V
	Chip Enable Low, Output ON, $V_{IN} = 2.3V$ to $6.0V$ Chip Enable High, Output OFF, $V_{IN} = 2.3V$ to $6.0V$	$V_{ENL}$			0.4	

Note 1: Specifications are production tested at  $TA=25^{\circ}C$ . Specifications over the  $-40^{\circ}C$  to  $85^{\circ}C$  operating temperature range are assured by design, characterization and correlation with Statistical Quality Controls (SQC).

Note 2: Connecting a 22nF bypass capacitor to BP pin can improve SULR1190 PSRR in High frequency.

Typical Performance Characteristics

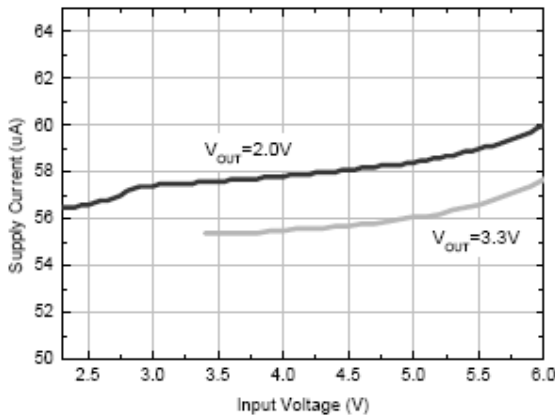


Fig. 1 Supply Current vs. Input Voltage

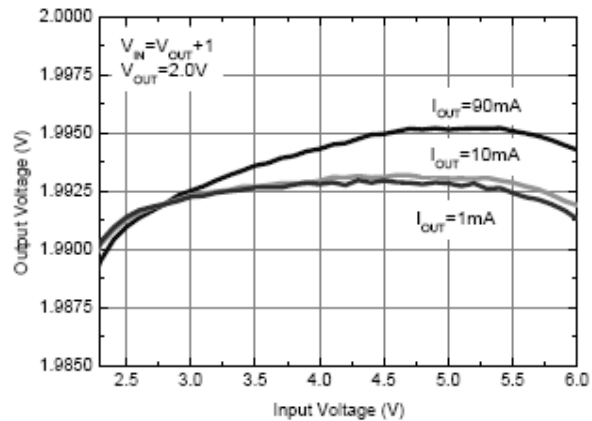


Fig. 2 Output Voltage vs. Input Voltage

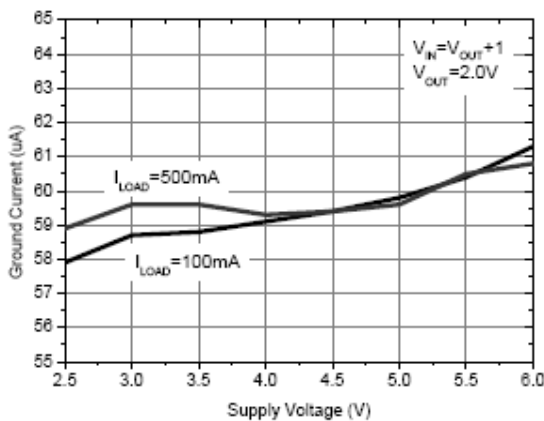


Fig. 3 Ground Current

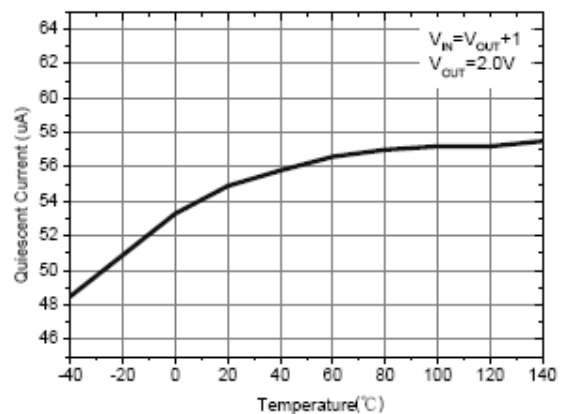


Fig. 4 Quiescent Current vs. Temperature

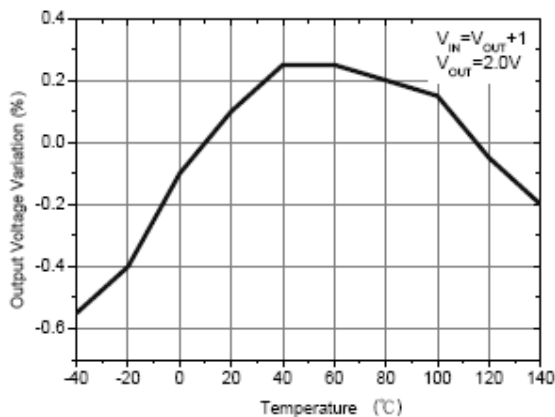


Fig. 5 Output Voltage vs. Temperature

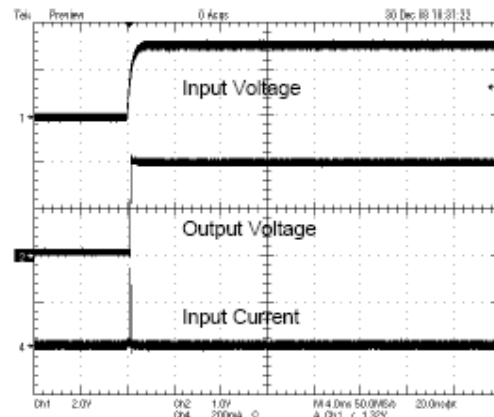


Fig. 6 Start-up waveform without bypass capacitance



Technical Data  
Data Sheet N1577, Rev. -  
Typical Performance Characteristics (Continued)

Ultra LDO 1A Linear Regulator With

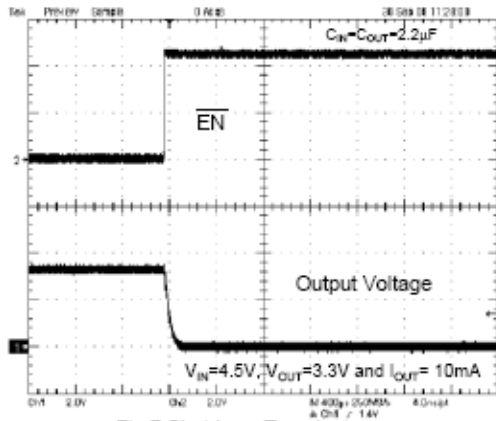


Fig.7 Shutdown Transient

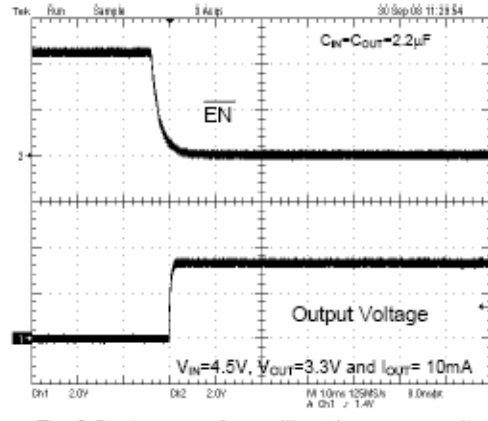


Fig. 8 Start-up waveform without bypass capacitor

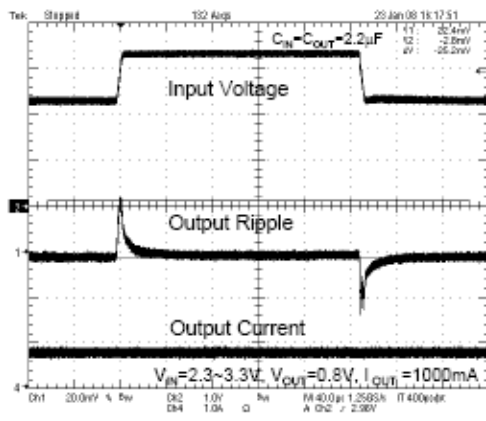


Fig. 9 Line Transient

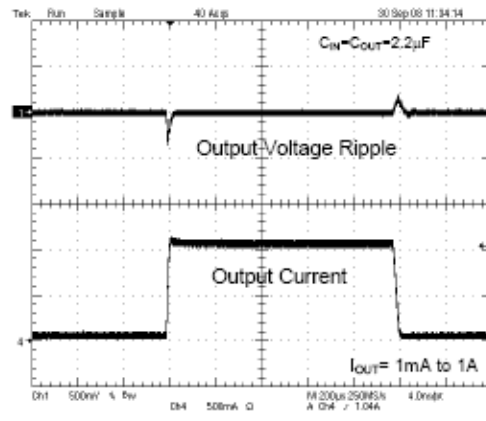


Fig.10 Load Transient Response at  $V_{IN}=4.3V$ ,  $V_{OUT}=3.3V$

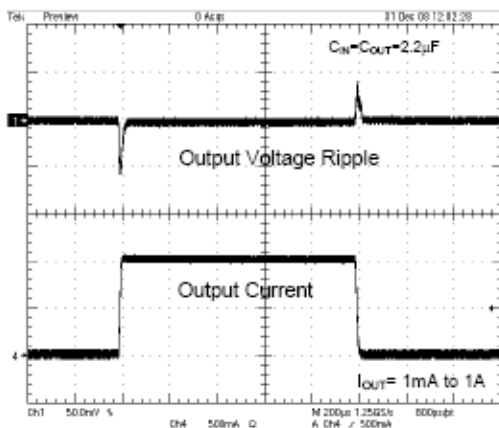


Fig.11 Load Transient Response at  $V_{IN}=2.3V$ ,  $V_{OUT}=0.8V$

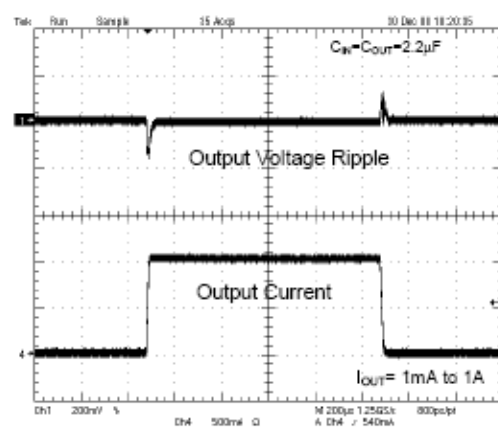


Fig.12 Load Transient Response at  $V_{IN}=3.0V$ ,  $V_{OUT}=2.0V$

Typical Performance Characteristics (Continued)

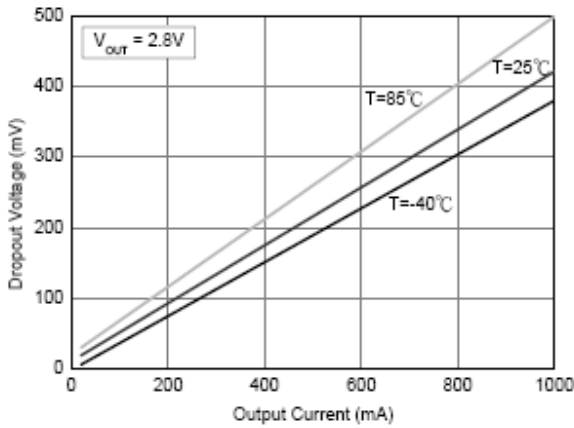


Fig. 13 Dropout Voltage vs. Output Current

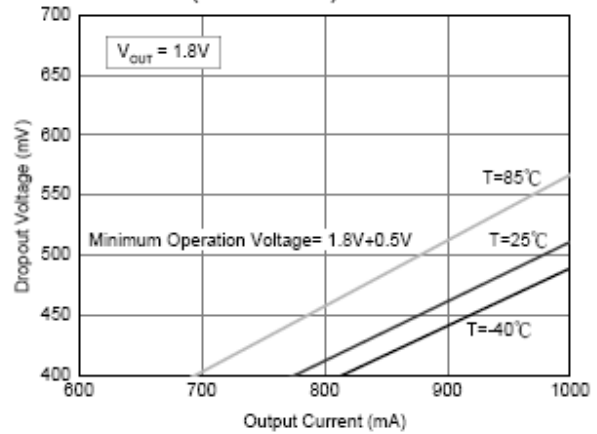


Fig. 14 Dropout Voltage vs. Output Current

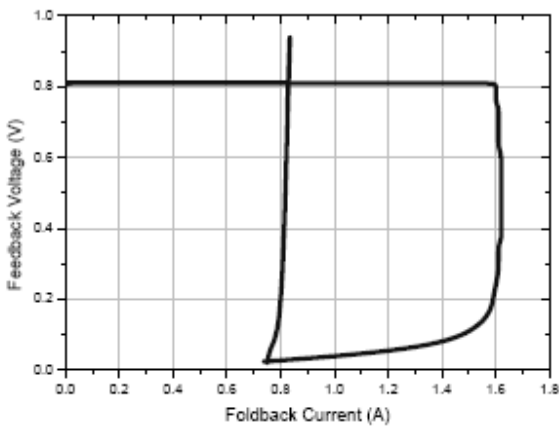


Fig. 15 Current Fold back ( $V_{out} < 0.2V$ )

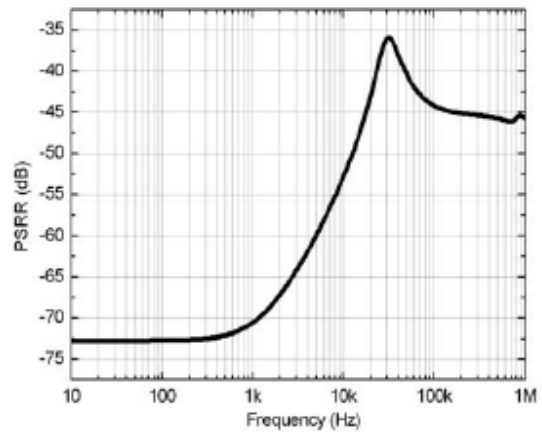
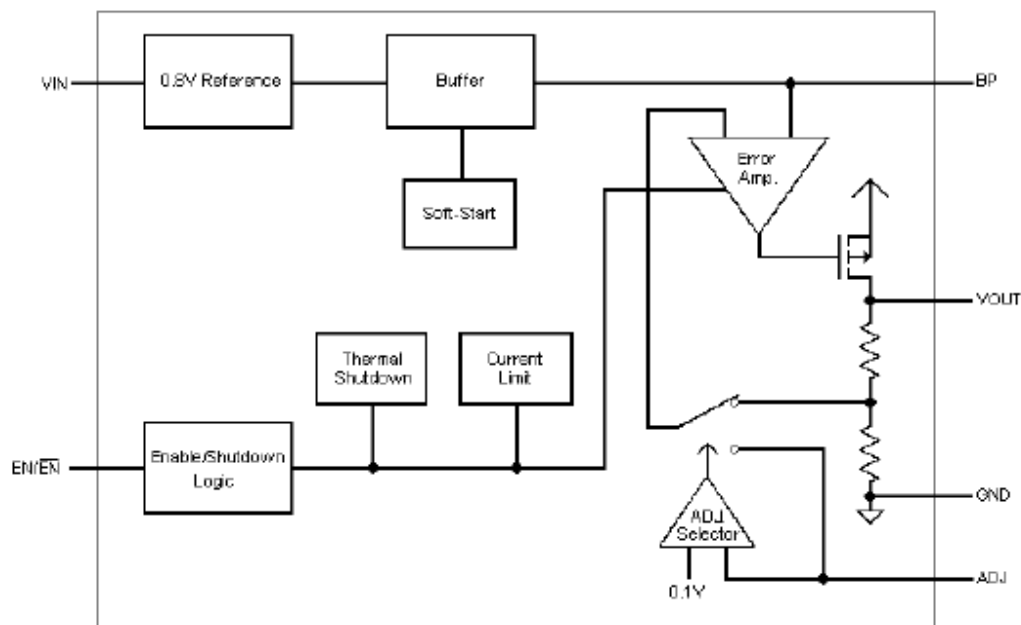


Fig. 16 PSRR Curve

### Block Diagram



### Pin Descriptions

- VIN** – Power supply input pin. Bypass with a 2.2 $\mu$ F capacitor to GND
- GND** – Ground.
- VOUT** – Regulator Output pin. Sources up to 1A.
- EN (5 Pin and 8 Pin)** – Chip Enable (Active Low). This pin isn't allowed to float.
- EN (5 Pin and 8 Pin)** – Chip Enable (Active High). This pin isn't allowed to float.
- BP (5 Pin and 8 Pin)** – Bypass pin. It can connect to external 22nF capacitor to GND to reduce output noise. The bypass pin could be floating if it's unnecessary (Keep floating cannot pull low and pull high).
- ADJ (5 Pin and 8 Pin)** – The output voltage can either be set by the internal feedback resistors when this pin is grounded, or be set by the external feedback resistors when using a resistive divider.



## Application Information

The SULR1190 is a high performance linear regulator that provides low-dropout voltage and low quiescent-current. The device is available in an adjustable version and fixed output voltages ranging from 1.2V to 3.8V, and the device can supply loads up to 1A.

### SHUTDOWN

By connecting  $\overline{\text{EN}}$ (EN) pin to  $V_{\text{IN}}$ (ground), the SULR1190 can be shut down to reduce the supply current to 0.1 $\mu$ A(typ.). At this operation mode, the output voltage of SULR1190 is equal to 0V.

### CURRENT LIMIT

The SULR1190 includes a current limiter, which monitors and controls the maximum output current. If the output is overloaded or shorted to ground, this can protect the device from being damaged.

### THERMAL PROTECTION

The SULR1190 includes a thermal-limiting circuit, which is designed to protect the device against overload condition. When the junction temperature exceeds  $T_J=150^\circ\text{C}$ , the thermal-limiting circuit turns off the pass transistor and allows the IC to cool. For continuous load condition, maximum rating of junction temperature must not be exceeded.

### INPUT-OUTPUT CAPACITORS

Linear regulators require input and output capacitors to maintain stability. Input capacitor at 2.2 $\mu$ F with a 2.2 $\mu$ F ceramic output capacitor is recommended. When choosing the input and output ceramic capacitors, X5R and X7R types are recommended because they retain their capacitance over wider ranges of voltage and temperature than other types.

### NOISE BYPASS CAPACITOR

A 22nF bypass capacitor at BP pin can reduce output voltage noise. The bypass pin can be floating if it's unnecessary.

### OUTPUT VOLTAGE PROGRAMMING

The output voltage of SULR1190 linear regulator can be set by its internal feedback resistors when the ADJ pin is grounded. In addition, the output voltage of SULR1190 linear regulator can be set by the external feedback resistors when connecting a resistive divider  $R_1$  and  $R_2$ . While connecting a resistive divider,  $V_{\text{OUT}}$  can be calculated as:

$$V_{\text{OUT}} = 0.8 \times \left\{ 1 + \frac{R_1}{R_2} \right\}$$

The resistive divider should sit as close to ADJ pin as possible.

### POWER DISSIPATION

The maximum power dissipation of SULR1190 depends on the thermal resistance of its case and circuit board, the temperature difference between the die junction and ambient air, and the rate of airflow. The rate of temperature rise is greatly affected by the mounting pad configuration on the PCB, the board material, and the ambient temperature. When the IC mounting with good thermal conductivity is used, the junction temperature will be low even when large power dissipation applies.

The power dissipation across the device is  $P = I_{\text{OUT}}(V_{\text{IN}} - V_{\text{OUT}})$ .



The maximum power dissipation is:

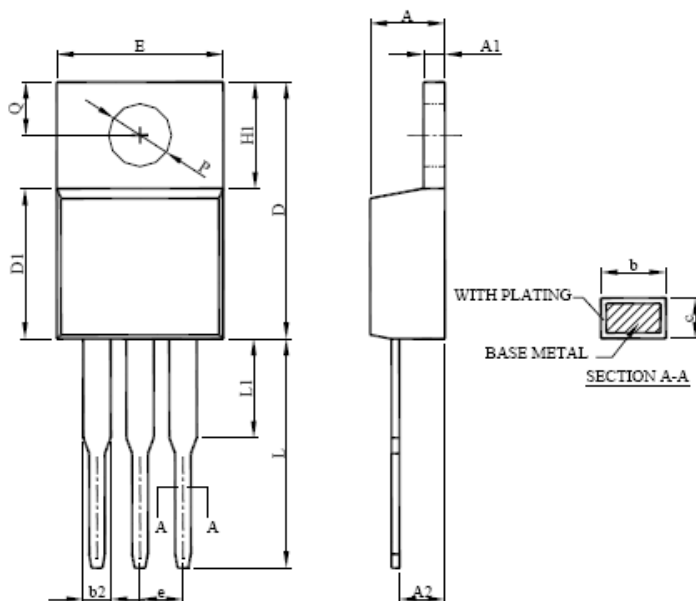
$$P_{MAX} = \frac{(T_{J-max} - T_A)}{R_{\theta JA}}$$

Where  $T_{J-max}$  is the maximum allowable junction temperature (150°C), and  $T_A$  is the ambient temperature suitable in application.

As a general rule, the lower temperature is, the better reliability of the device is. So the PCB mounting pad should provide maximum thermal conductivity to maintain low device temperature.

Physical Dimensions

TO-220 (unit: mm)

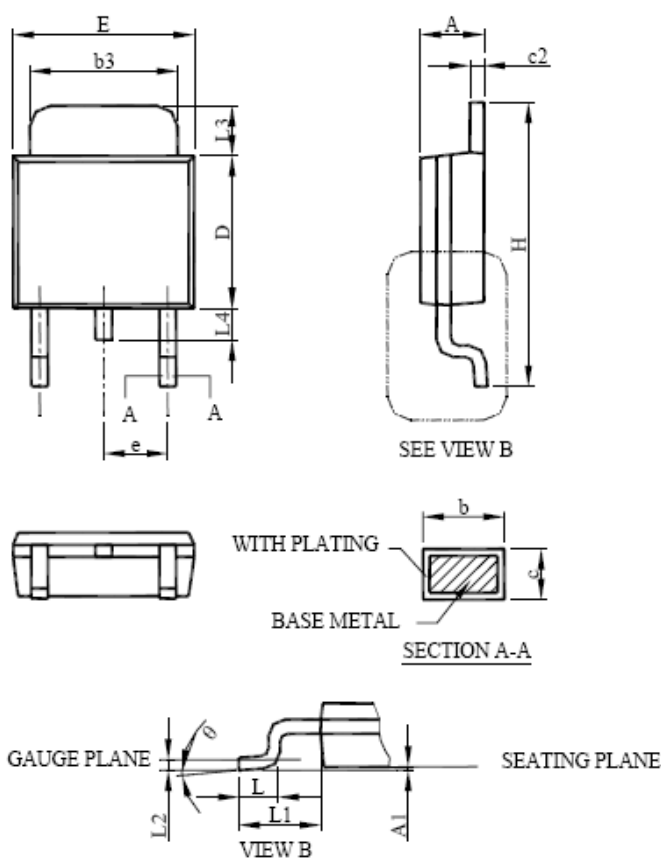


SYMBOL	TO-220	
	MILLIMETERS	
	MIN.	MAX.
A	3.56	4.82
A1	0.51	1.39
A2	2.04	2.92
b	0.38	1.01
b2	1.15	1.77
c	0.35	0.61
D	14.23	16.51
D1	8.38	9.02
E	9.66	10.66
e	2.54 BSC	
H1	5.85	6.85
L	12.70	14.73
L1	--	6.35
P	3.54	4.08
Q	2.54	3.42

Note:

1. Refer to JEDEC TO-220AB.
2. Dimension "E" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side.
3. Dimension "D1" does not include inter-lead flash or protrusions.
4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.

TO-252 (unit: mm)

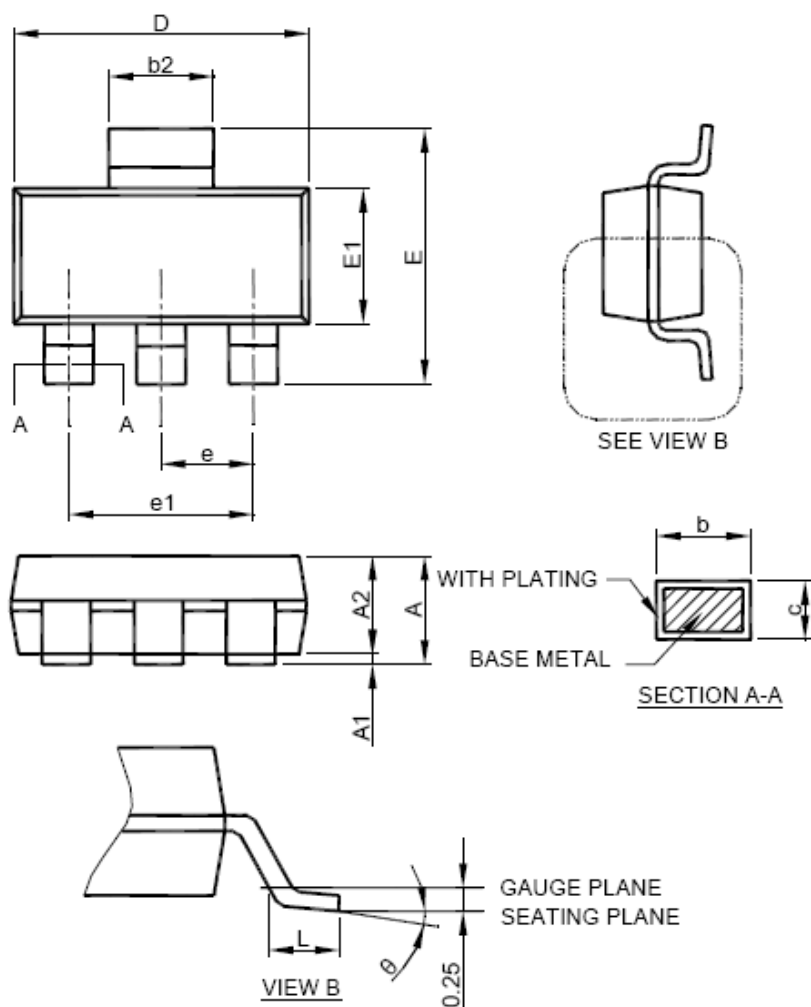


SYMBOL	TO-252-3L	
	MILLIMETERS	
	MIN.	MAX.
A	2.19	2.38
A1	0.00	0.13
b	0.64	0.89
b3	4.95	5.46
c	0.46	0.61
c2	0.46	0.89
D	5.33	6.22
E	6.35	6.73
e	2.28 BSC	
H	9.40	10.41
L	1.40	1.78
L1	2.67 REF	
L2	0.51 BSC	
L3	0.89	2.03
L4	--	1.02
$\theta$	0°	8°

Note:

1. Refer to JEDEC TO-252AA and AB.
2. Dimension "E" do not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side.
3. Dimension "D" does not include inter-lead flash or protrusions.
4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.

SOT-223(unit: mm)

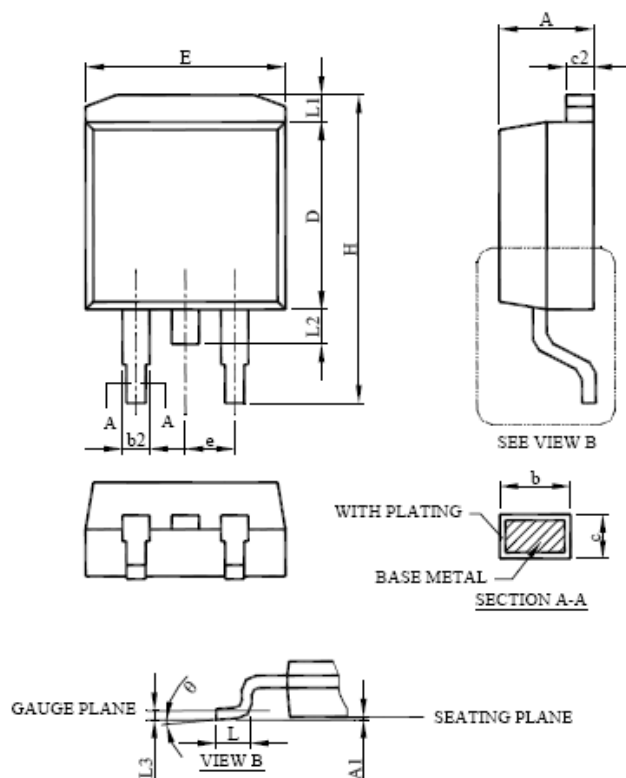


SYMBOL	SOT-223	
	MILLIMETERS	
	MIN.	MAX.
A		1.80
A1	0.02	0.10
A2	1.55	1.65
b	0.66	0.84
b2	2.90	3.10
c	0.23	0.33
D	6.30	6.70
E	6.70	7.30
E1	3.30	3.70
e	2.30 BSC	
e1	4.60 BSC	
L	0.90	
$\theta$	0°	8°

- Note: 1. Refer to JEDEC TO-261AA.  
 2. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side .  
 3. Dimension "E1" does not include inter-lead flash or protrusions.  
 4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.



TO-263 (unit: mm)

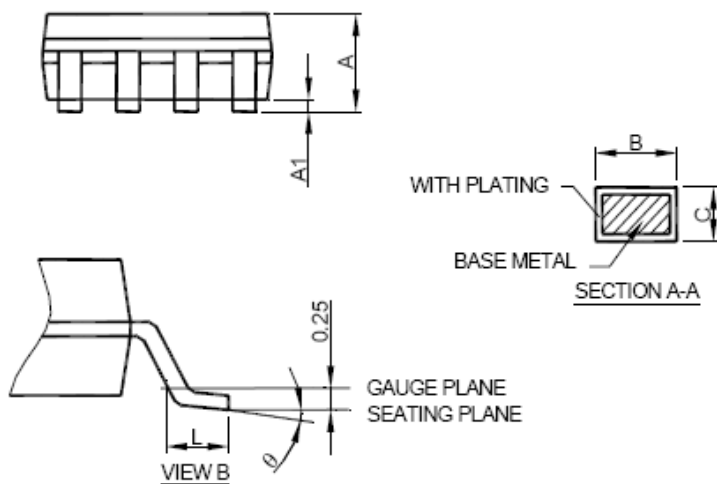
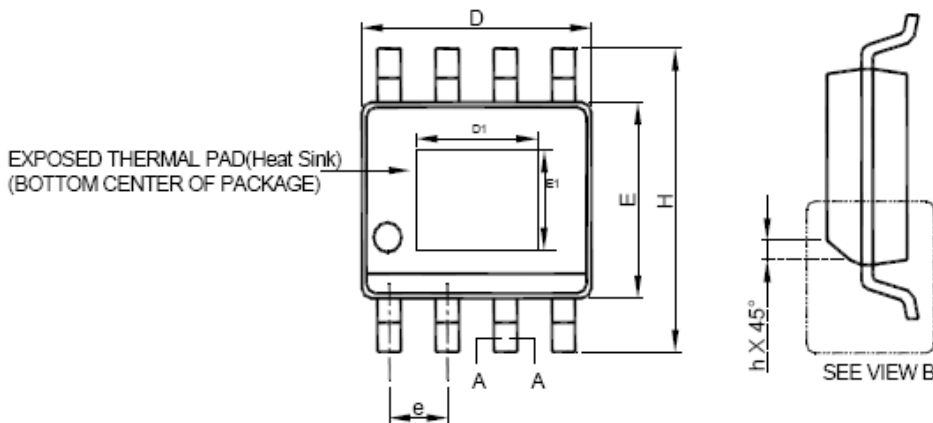


SYMBOL	TO-263-3L	
	MILLIMETERS	
	MIN.	MAX.
A	4.06	4.83
A1	0.00	0.25
b	0.51	0.99
b2	1.14	1.78
c	0.38	0.74
c2	1.14	1.65
D	8.38	9.65
E	9.65	10.67
e	2.54 BSC	
H	14.61	15.88
L	1.78	2.79
L1	--	1.68
L2	--	1.78
L3	0.25 BSC	
θ	0°	8°

Note:

1. Refer to JEDEC TO-263AB.
2. Dimension "E" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side.
3. Dimension "D" does not include inter-lead flash or protrusions.
4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.

SOP-8 (unit: mm)



SYMBOL	SOP-8 Exposed Pad(Heat Sink)	
	MILLIMETERS	
	MIN.	MAX.
A	1.35	1.75
A1	0.00	0.15
B	0.31	0.51
C	0.17	0.25
D	4.80	5.00
D1	1.50	3.50
E	3.80	4.00
E1	1.0	2.55
e	1.27 BSC	
H	5.80	6.20
h	0.25	0.50
L	0.40	1.27
θ	0°	8°

- Note: 1. Refer to JEDEC MS-012E.  
 2. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side .  
 3. Dimension "E" does not include inter-lead flash or protrusions.  
 4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.



SULR1190

Technical Data  
Data Sheet N1577, Rev. -

Ultra LDO 1A Linear Regulator With

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